

Technical characteristics

Independent research and development of software integration system, more compatibility

- Supports semi-automatic control (manual or automatic testing)
- Automatic wafer calibration, wafer mapping, die size measurement, alignment, and remote access to test data
- One-click automatic calibration of RF probe module, with automatic probe cleaning function
- One-click adaptive four-axis Chuck precision calibration, supporting micrometer-level pad point testing
- Supports single-point or continuous testing
- Strong data storage and processing capabilities
- Ability to divide test results into BIN values and identify NG devices
- Multiple system integration capabilities, allowing independent upgrades of operating systems, application systems, and device testing systems

Air film shock absorption system

The industry's unique internal integration of high-performance air film shock absorption system and the dual design of the external isolation barrier, effectively avoid the vibration caused by the operator's touch;In addition, a long-aging casting is used as the substrate to suppress the vibration in the process of motion at the fastest speed of 1S in the industry to ensure the stable operation of the equipment, and to ensure that the screen does not shake when the image is enlarged at 2000X;At the same time, the high-precision control valve ensures that the height error of the moving part of the platform is 0.1mm, effectively realizing the test ability of fast die to die, ensuring that the whole system can still maintain a stable running state when moving at a high speed, and greatly improving the test efficiency.

Industry leading 3 times imaging technology

12:1 fast and precise motorized zoom microscope, zoom range 0.6~7.2X, image resolution 3.05μm, total magnification range 33X~396X.